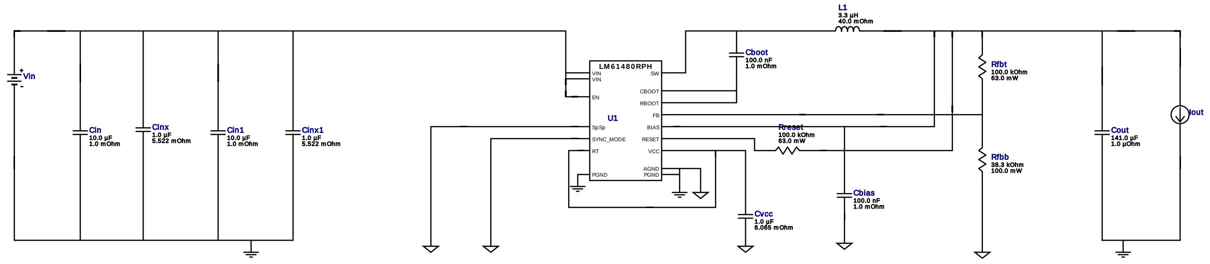
TEXAS INSTRUMENTS

WEBENCH ® Design Report

VinMin = 10.0V
VinMax = 35.0V
Vout = 3.6V
Iout = 1.0A

Device = LM61480RPHR
Topology = Buck
Created = 2024-08-01 14:23:31.431
BOM Cost = NA
BOM Count = 13
Total Pd = 0.6W

Design : 25 LM61480RPHR
LM61480RPHR 10V-35V to 3.60V @ 1A



Design Alerts

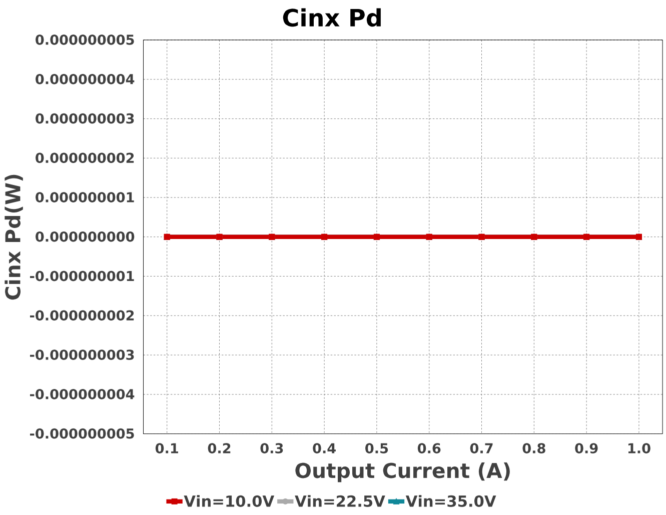
Component Selection Information

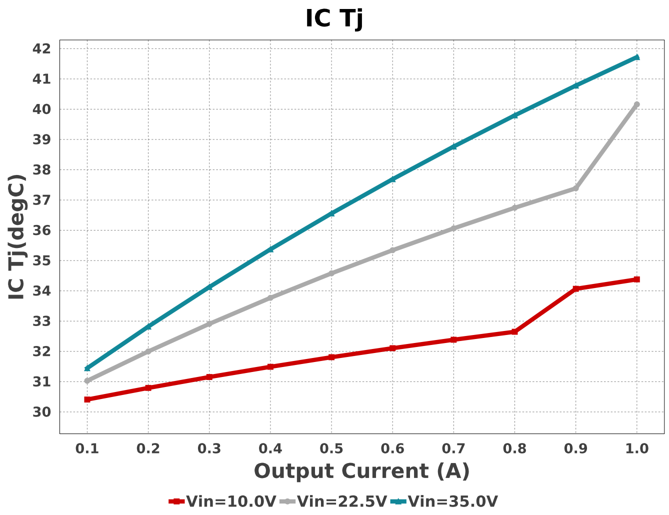
This device can work in steady state at Vin = 3V. However, needs a minimum of 3.6V during start up. See datasheet for details.

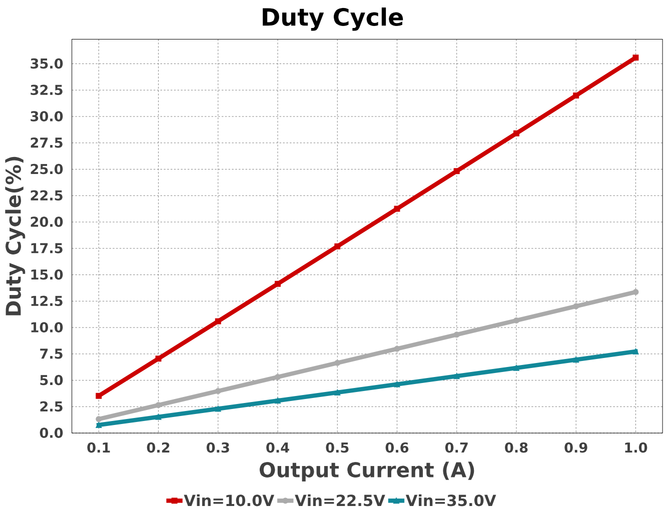
Electrical BOM

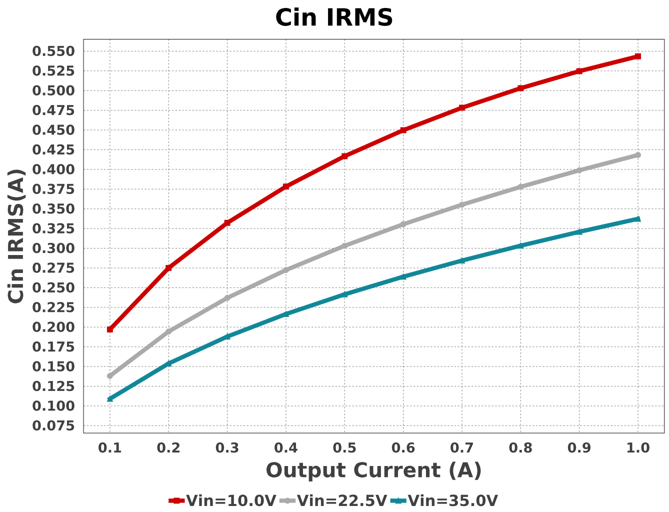
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbias	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cboot	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	$0.01	0402 3 mm^2
Cin	MuRata	GRM32ER71H106KA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	1	$0.47	1210_270 15 mm^2
Cin1	MuRata	GRM32ER71H106KA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	1	$0.47	1210_270 15 mm^2
Cinx	TDK	C1608X5R1H105K080AB Series= X5R	Cap= 1.0 uF ESR= 5.522 mOhm VDC= 50.0 V IRMS= 2.2162 A	1	$0.03	0603 5 mm^2
Cinx1	TDK	C1608X5R1H105K080AB Series= X5R	Cap= 1.0 uF ESR= 5.522 mOhm VDC= 50.0 V IRMS= 2.2162 A	1	$0.03	0603 5 mm^2
Cout	CUSTOM	CUSTOM Series= ?	Cap= 141.0 uF ESR= 1.0 uOhm VDC= 5.4 V IRMS= 1.27217 A	1	NA	CUSTOM 0 mm^2
Cvcc	MuRata	GRM188R60J105KA01D Series= X5R	Cap= 1.0 uF ESR= 6.065 mOhm VDC= 6.3 V IRMS= 1.36934 A	1	$0.01	0603 5 mm^2
L1	NIC Components	NPI54C3R3MTRF	L= 3.3 µH 40.0 mOhm	1	$0.09	IND_NPI54C 61 mm^2
Rfbb	Vishay-Dale	CRCW060338K3FKEA Series= CRCW..e3	Res= 38.3 kOhm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm^2

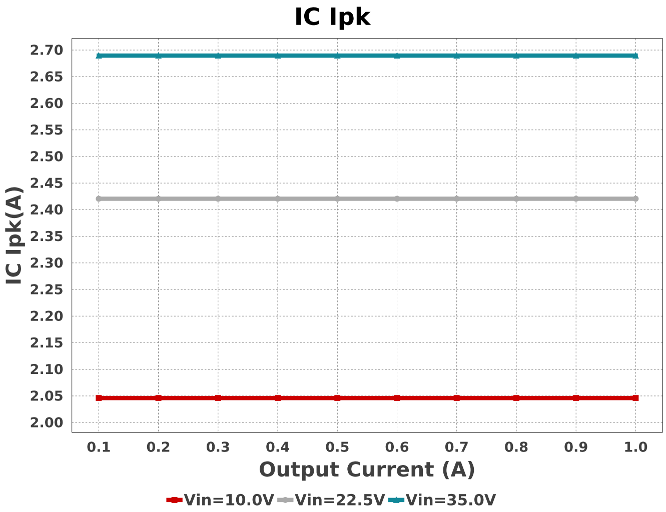
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbt	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
Rreset	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	LM61480RPHR	Switcher	1	$1.81	RPH0016A 25 mm^2

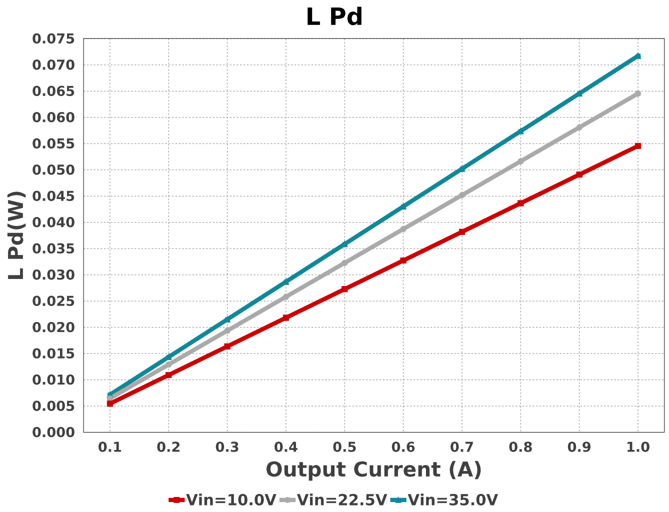


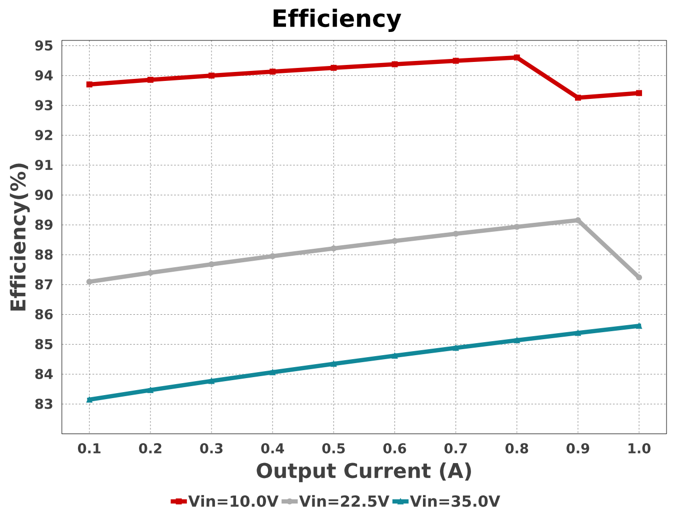


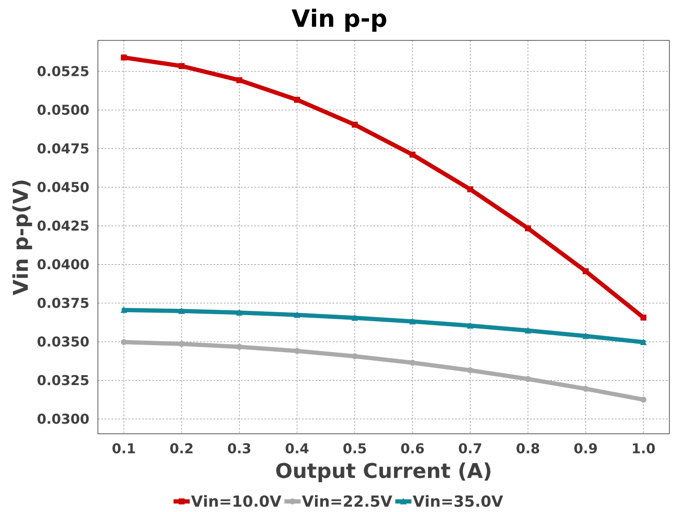


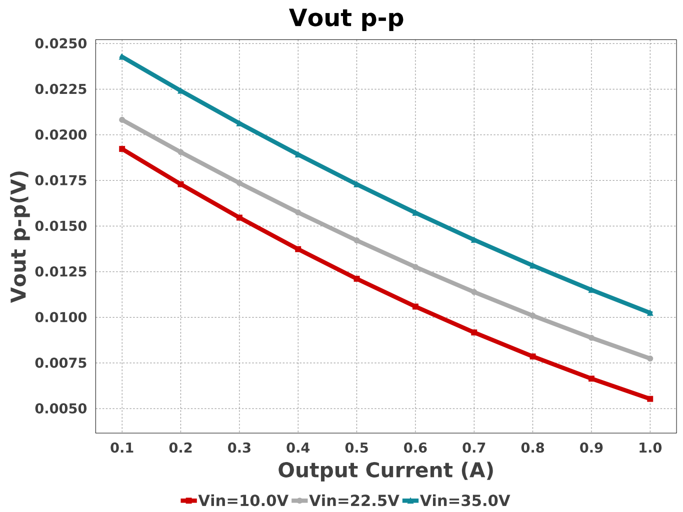


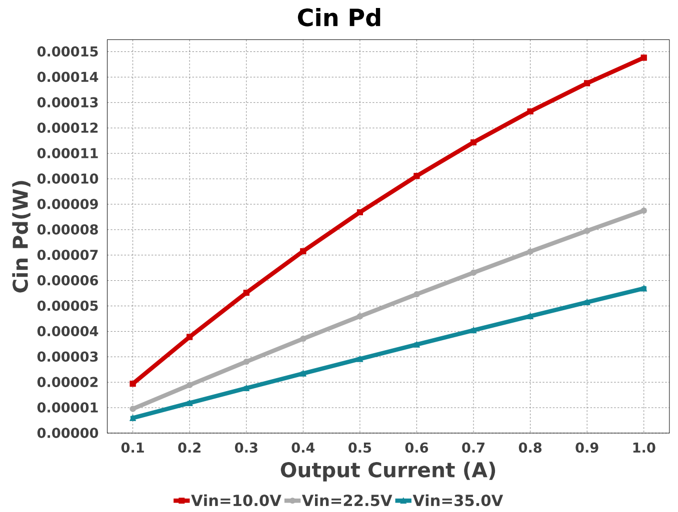


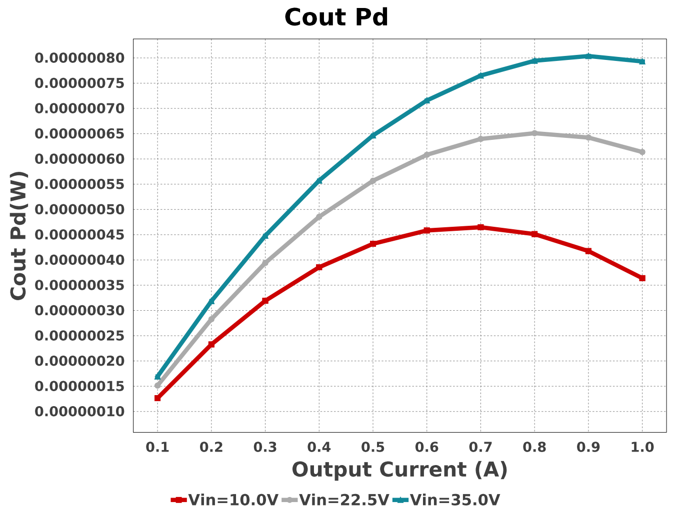


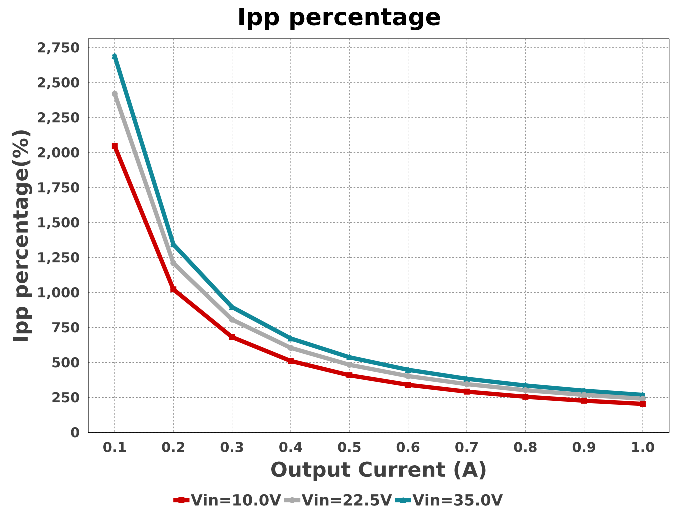

Efficiency
Efficiency(%)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V


Vin p-p
Vin p-p(V)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V

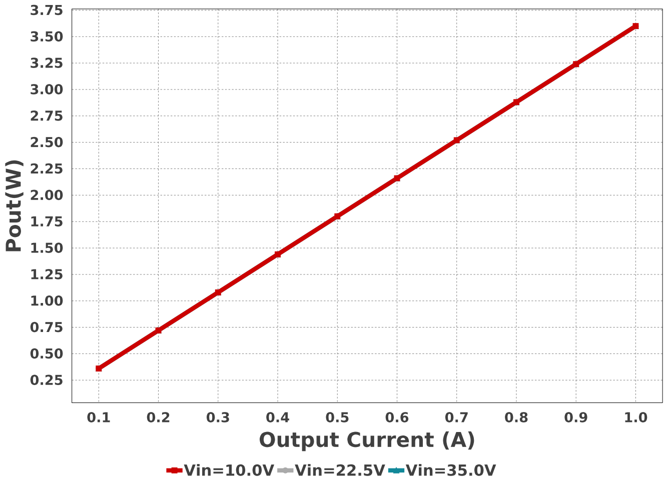

Vout p-p
Vout p-p(V)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V


Cin Pd
Cin Pd(W)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V

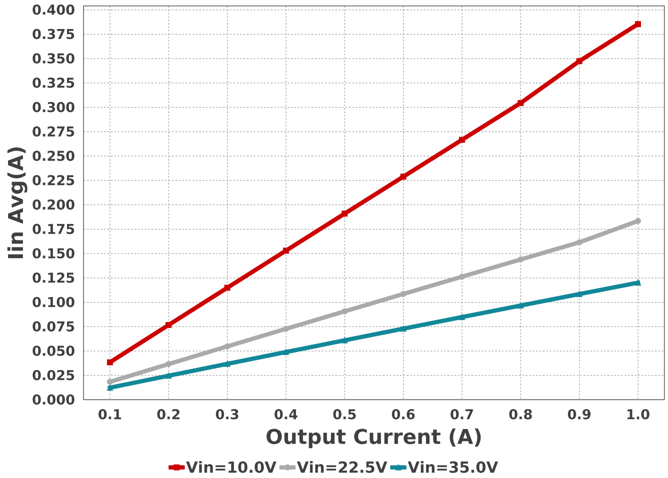

Cout Pd
Cout Pd(W)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V


Ipp percentage
Ipp percentage(%)
Output Current (A)
Vin=10.0V Vin=22.5V Vin=35.0V

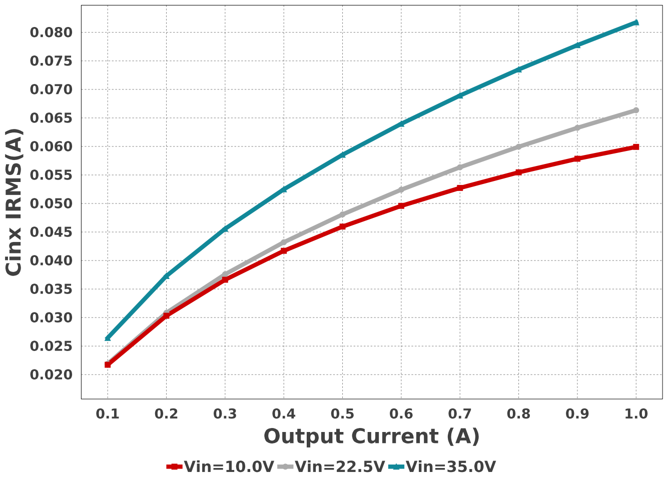
Pout



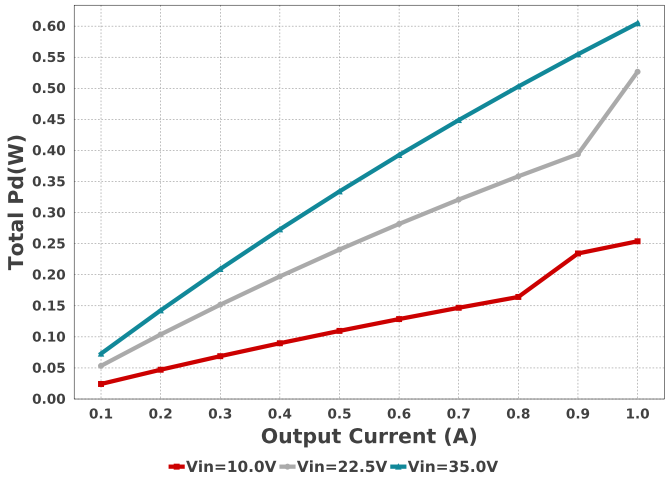
Iin Avg



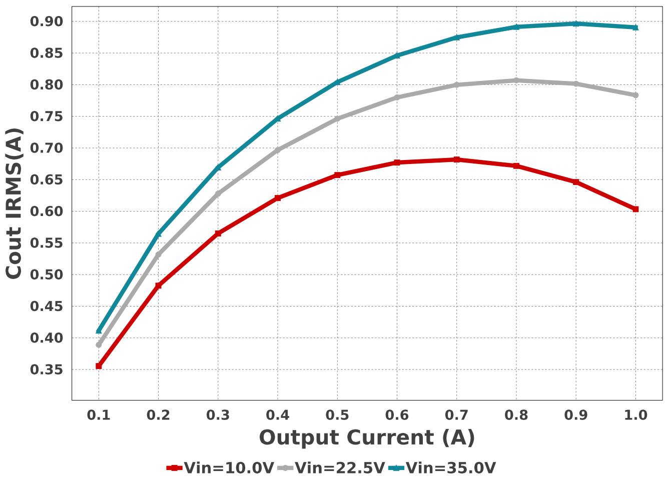
Cinx IRMS



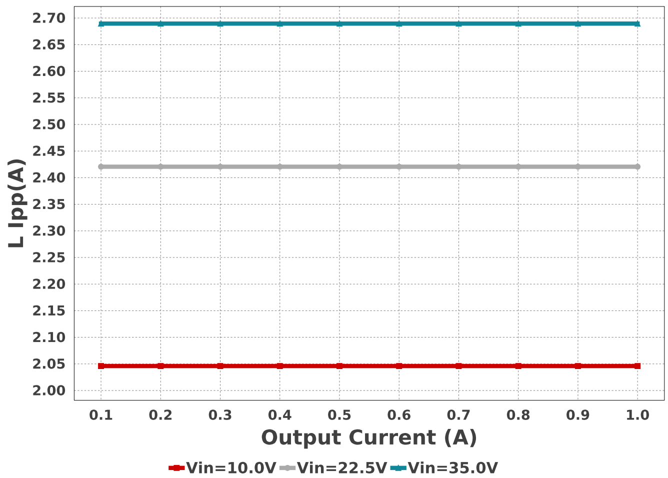
Total Pd

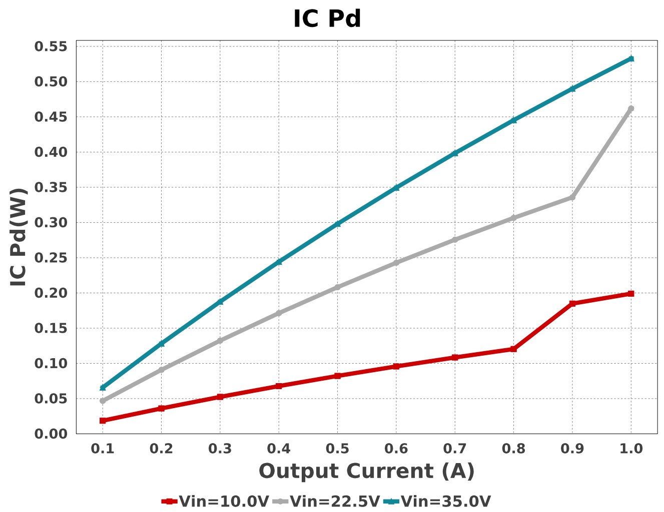


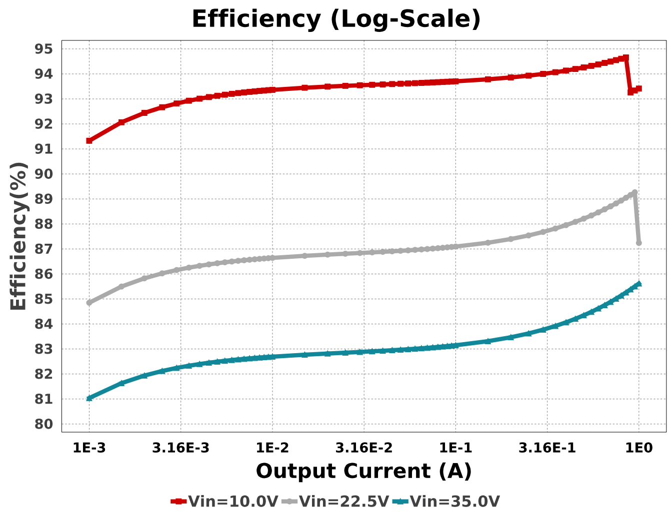
Cout IRMS



L Ipp







Operating Values

#	Name	Value	Category	Description
1.	BOM Count	13		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	337.356 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	56.905 µW	Capacitor	Input capacitor power dissipation
5.	Cinx IRMS	81.76 mA	Capacitor	Bulk capacitor RMS ripple current
6.	Cinx Pd	0.0 W	Capacitor	Bulk capacitor power dissipation
7.	Cout IRMS	890.519 mA	Capacitor	Output capacitor RMS ripple current
8.	Cout Pd	793.02 nW	Capacitor	Output capacitor power dissipation
9.	IC Ipk	2.69 A	IC	Peak switch current in IC
10.	IC Pd	532.8 mW	IC	IC power dissipation
11.	IC Tj	41.722 degC	IC	IC junction temperature
12.	ICThetaJA Effective	22.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
13.	Iin Avg	120.13 mA	IC	Average input current
14.	Ipp percentage	268.953 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
15.	L Ipp	2.69 A	Inductor	Peak-to-peak inductor ripple current
16.	L Pd	71.721 mW	Inductor	Inductor power dissipation
17.	Cin Pd	56.905 µW	Power	Input capacitor power dissipation
18.	Cinx Pd	0.0 W	Power	Bulk capacitor power dissipation
19.	Cout Pd	793.02 nW	Power	Output capacitor power dissipation
20.	IC Pd	532.8 mW	Power	IC power dissipation
21.	L Pd	71.721 mW	Power	Inductor power dissipation
22.	Total Pd	604.656 mW	Power	Total Power Dissipation
23.	Duty Cycle	7.734 %	System Information	Duty cycle
24.	Efficiency	85.619 %	System Information	Steady state efficiency
25.	FootPrint	246.0 mm^2	System Information	Total Foot Print Area of BOM components
26.	Frequency	273.257 kHz	System Information	Switching frequency
27.	Iout	1.0 A	System Information	Iout operating point
28.	Mode	PFM	System Information	Conduction Mode
29.	Pout	3.6 W	System Information	Total output power
30.	Vin	35.0 V	System Information	Vin operating point
31.	Vin p-p	34.973 mV	System Information	Peak-to-peak input voltage
32.	Vout	3.6 V	System Information	Operational Output Voltage
33.	Vout Actual	3.611 V	System Information	Vout Actual calculated based on selected voltage divider resistors
34.	Vout Tolerance	2.475 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
35.	Vout p-p	10.245 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	35.0	Maximum input voltage
VinMin	10.0	Minimum input voltage
VinTyp	12.0	Typical input voltage
Vout	3.6	Output Voltage
base_pn	LM61480	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

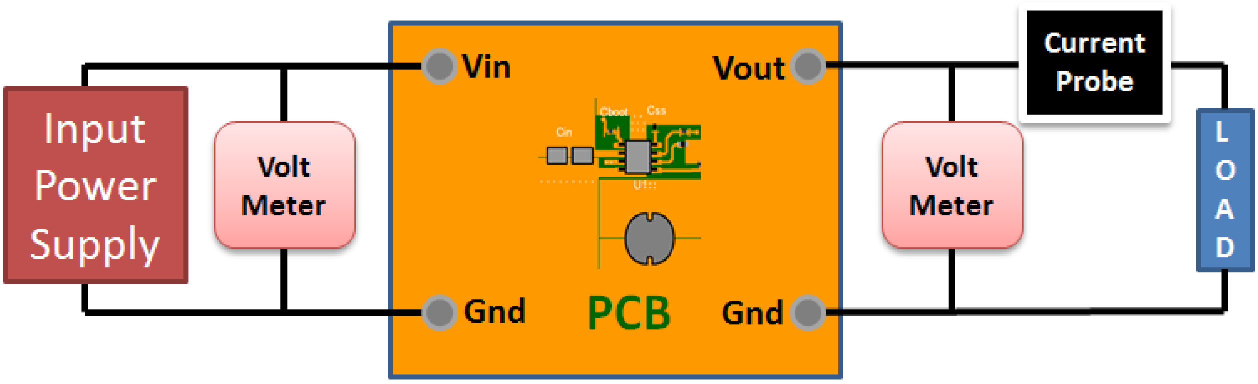
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 10.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

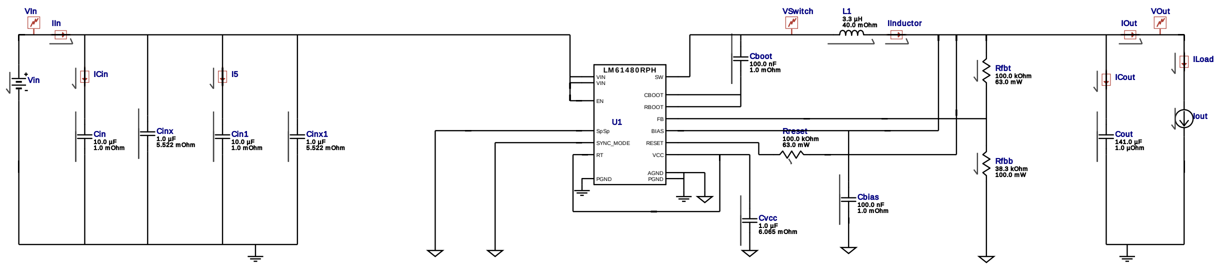


WEBENCH® Electrical Simulation Report

Design Id = 25

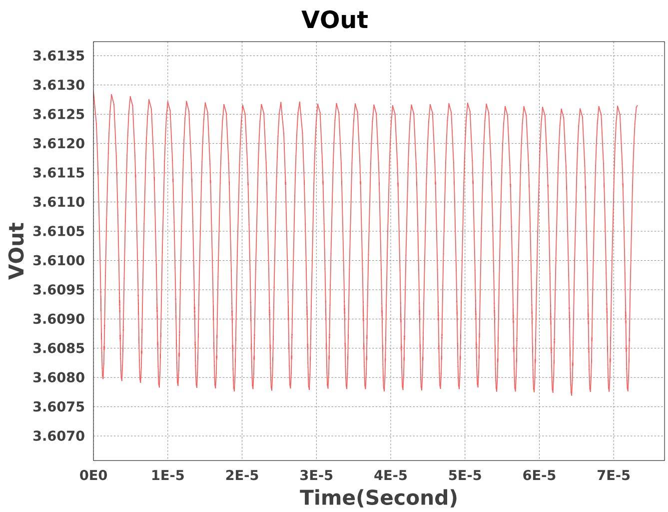
sim_id = 8

Simulation Type = Steady State



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	L1	IC	Initial Current	1.0 A
2.	Iout	I	Output Current	1.0 A



Design Assistance

1. The LM61480 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. This device can work in steady state at Vin = 3V. However, needs a minimum of 3.6V during start up. See datasheet for details The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application

2. Master key : E8A119AE42F0E3FD181D45ED1F5A0C7F[v1]

3. **LM61480** Product Folder : http://www.ti.com/product/LM61480 : contains the data sheet and other resources.

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